

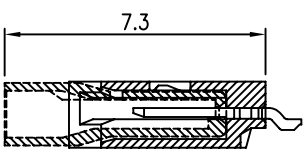
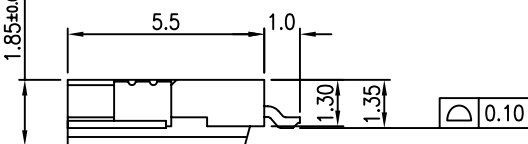
SECT. Y-Y

- NOTES:
- MATERIAL:
 - HOUSING: HALEGEN FREE PLASTIC, HIGH TEMP., UL94V-0.
 - CONTACT: COPPER ALLOY
 - FITTING NAIL: COPPER ALLOY
 - FINISH:
 - CONTACT: 50~100u" NICKEL UNDERPLATING OVERALL.
 - 1: GOLD FLASH (1~3u").
 - N: 100~200u" MATT TIN,
 - L: 100~200u" TIN.
 - D: 30u" GOLD ON CONTACT AREA
 - T: 10u" GOLD ON CONTACT AREA
 - FITTING NAIL: 50~100u" NICKEL UNDERPLATING OVERALL.
 - 1: GOLD FLASH (1~3u").
 - N: 100~200u" MATT TIN PLATING,
 - L: 100~200u" TIN PLATING.
 - D: GOLD FLASH ON SOLDER AREA
 - T: GOLD FLASH ON SOLDER AREA
 - REFLOW SOLDER CAPABLE TO 260°C PER ACES SPEC.
 - SPEC. PLS. REFER TO PS-50278-xxxxx-xxx
 - PACKAGE PLS. REFER TO 88230-XX0X-XX-TRP
 - PART NUMBER
 - THE NUMBER OF WINDOWS: 2. 3PIN IS ONE, 4PIN AND OTHER IS TWO.

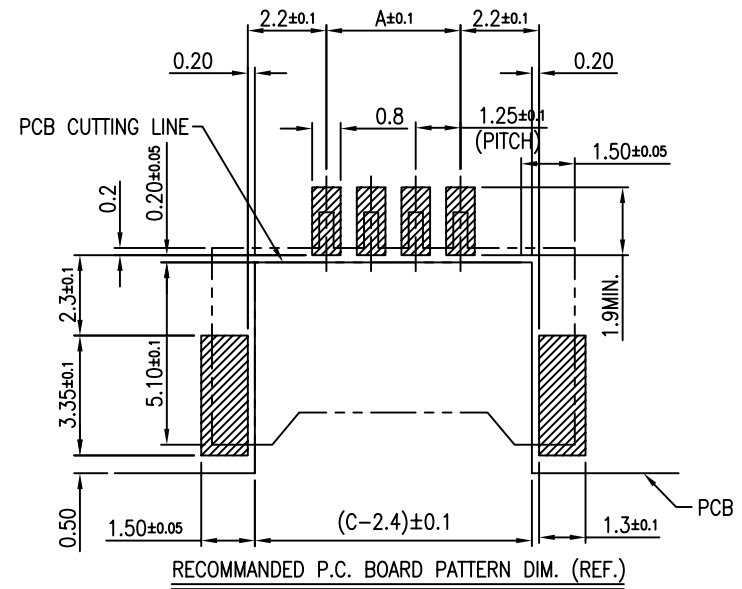
P/N LEGEND

50277-XXX	X	X-XXX	XXX	Material&Color
			001	HF Plastic&Black

- No Of CKT
- Packing
- 0: Tape & Reel
 - 1: Tube
 - 4: Tape & Reel with Mylar
- PLATING
- L: Lead Free (Pure Tin)
 - N: Matt Tin (lead free)
 - 1: Gold Flash (lead free)
 - D: 30u" Gold on contact area and gold flash on solder area
 - T: 10u" Gold on contact area and gold flash on solder area



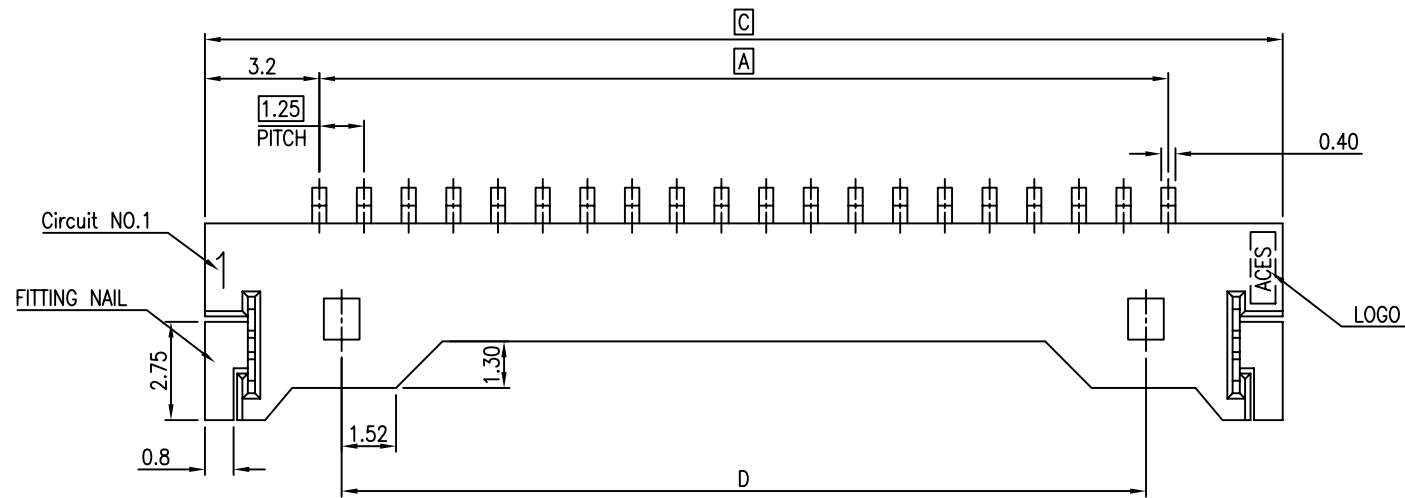
MATED CONDITION



RECOMMENDED P.C. BOARD PATTERN DIM. (REF.)

CKT.	DIM A	DIM B	DIM C	DIM D	M/SIZE
2	1.25	3.77	7.65	--	W3T12
3	2.50	5.02	8.90	--	W3T12
4	3.75	6.27	10.15	2.50	W6T12
5	5.00	7.52	11.40	3.75	W6T12
6	6.25	8.77	12.65	5.00	W6T12
7	7.50	10.02	13.90	6.25	WAT12
8	8.75	11.27	15.15	7.50	WAT12
9	10.00	12.52	16.40	8.75	WAT12
10	11.25	13.77	17.65	10.00	WCT12
12	13.75	16.27	20.15	12.50	X
14	16.25	18.77	22.65	15.00	X
15	17.50	20.02	23.90	16.25	X
16	18.75	21.27	25.15	17.50	X
18	21.25	23.77	27.65	20.00	X
20	23.75	26.27	30.15	22.50	X

一般公差 TOLERANCES X ±0.5 XX ±0.15 X ±0.25 XXX ±0.1 ANGLES ±2°		宏致電子股份有限公司 Aces Electronics Co.,Ltd.	
檢驗尺寸標示 SYMBOLS (C) (M) INDICATE CLASSIFICATION DIMENSION (C) MARK IS CRITICAL DIM. (M) MARK IS MAJOR DIM.	品名 (TITLE) 1.25mm WIRE TO BOARD WAFER LPF-1 SMT R/A TYPE	製圖 (DR) '15/12/17 審核 (CHKD) BRAVE	CHENYA
表面處理 (FINISH)	圖號 (DWG.NO) 50277-XXXXX-XXX	核准 (APPD) FRANK	
比例 (SCALE) 單位 (UNITS)	5:1 mm	張數 (SHEET) 1 OF 2	SIZE REV A4 H



20PIN

一般公差 TOLERANCES X ±0.5 XX ±0.15 X ±0.25 XXX ±0.1 ANGLES ±2°		宏致電子股份有限公司 Aces Electronics Co.,Ltd.	
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表面處理 (FINISH)		圖號 (DWG.NO) 50277-XXXXX-XXX	核准 (APPD) FRANK
比例 (SCALE) 單位 (UNITS)		5:1 mm	張數 (SHEET) SIZE REV 2 OF 2 A4 H

单击下面可查看定价，库存，交付和生命周期等信息

[>>ACES \(宏致\)](#)